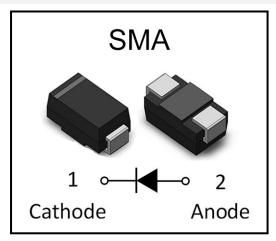


Fast Recovery Rectifier Diode

Features

Package

- · Super fast switching time for high efficinency
- · Low forward voltage drop
- · High current capability
- · High reliability
- High surge current capability
- Epitaxial construction



Description

· Case: molded plastic

· Polarity: Color band denotes cathode

• Package: SMA Plastic Package

Making Code



Ordering information

Part Number	US2A	US2B	US2D	US2G	US2J	US2K	US2M
Marking	US2A	US2B	US2D	US2G	US2J	US2K	US2M
Base qty	5K						







Fast Recovery Rectifier Diode

Maximum Ratings (@ T_A =25°C unless otherwise noted)

Symbol	Characteristics	US2A	US2B	US2D	US2G	US2J	US2K	US2M	Unit
V _{RRM}	Maximum Recurrent Peak Reverse Voltage		100	200	400	600	800	1000	V
V _{RMS}	Maximum RMS Voltage		70	140	280	420	560	700	V
V _{DC}	Maximum DC Blocking Voltage		100	200	400	600	800	1000	V
Maximum Average Forward Rectified		2.0							Α
I _(AV)	Current at T _L = 110°C	2.0							
Peak Forward Surge Current 8.3ms Single half		50						Α	
I-SM	I _{FSM} sine-waveSuperimposed on Rated Load		30						
V _F	Maximum Forward Voltage at 1.0A DC		1.0		1.3		1.7		V
I_R Maximum DC Reverse Current $T_J = 25^{\circ}C$ at Rated DC Blocking Voltage $T_J = 125^{\circ}C$		5						uA	
		100							
T _{RR}	Maximum Reverse Recovery Time(Note1)		50			100		nS	
CJ	Typical Junction Capacitance(Note2)		50						pF
R _{θJA}	Typical Thermal Resistance(Note3)		60						°C/W
TJ	Operating Temperature Range		-55 to +150						°C
T _{STG}	Storage Temperature Range			-5	55 to +15	0			°C

Notes:(1)Reverse recovery condition I_F =0.5A, I_R =1.0A, I_{RR} =0.25A.

- (2) Measured at 1.0 MHz and applied reverse voltage of 4.0V DC.
- (3)Thermal resistance junction to ambient.



Fast Recovery Rectifier Diode

Typical Performance Characteristics(T_J = 25 °C, unless otherwise noted)

Figure 1: Typical Forward Characteristics

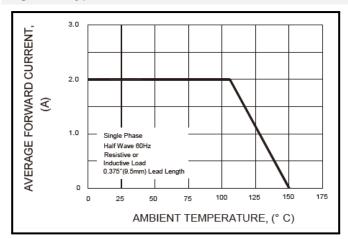


Figure 3: Forward Current Derating Curve

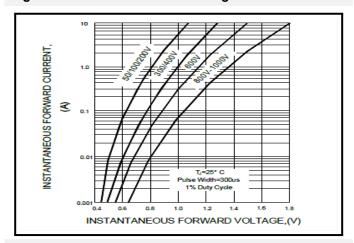


Figure 5: Typical Junction Capacitance

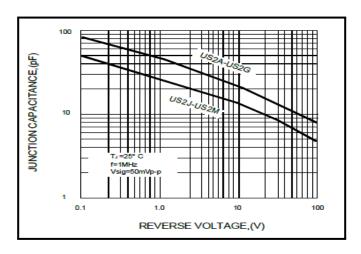


Figure 2: Typical Junction Capacitance

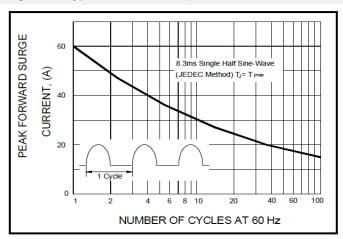


Figure 4: Peak Forward Surge Current

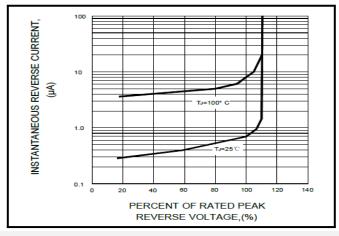
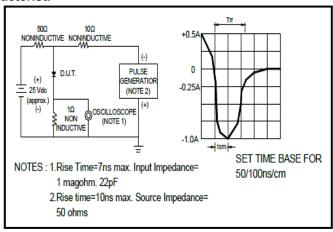


Figure 6: Test Circuit Diagram And Recover Time Char-

acteristi

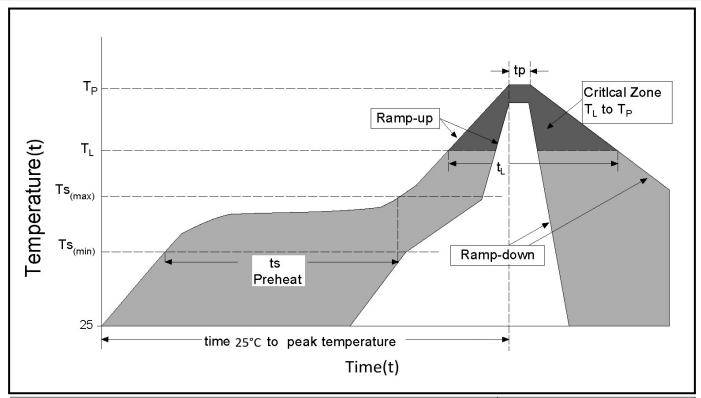


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Fast Recovery Rectifier Diode

Soldering Parameters

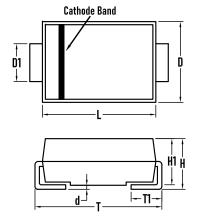


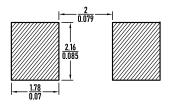
Reflow 0	Lead-free assembly	
	- Temperature Min (T _S (min))	150°C
Pre Heat	- Temperature Max (T _S (max))	200°C
	- Time (min to max) (t _S)	60 - 180 secs
Average ramp up rate (Li	3°C/second max	
T _S (max) to T _L - Ramp-up Rate		3°C/second max
Reflow	- Temperature (T _L) (Liquidus)	217°C
	- Time (t _L)	60 -150 secs
Peak Temperature (T _P)		260 ^{+0/-5°C}
Time within 5°C of actual peak Temperature (t _p)		20 -40 secs
Ramp-do	6°C/second max	
Time 25°C to peak Temperature (t)		8 minutes Max.
Do not exceed		260°C



Fast Recovery Rectifier Diode

Outline Drawing - SMA



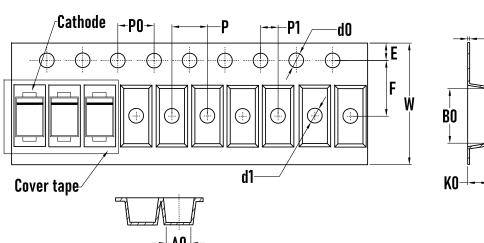


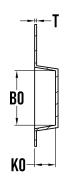
Note:

dimension: $\frac{mm}{inch}$

SYMBOL	MILLIN	/IETER	Inches		
STWIDUL	MIN.	MAX.	MIN.	MAX.	
D	2.5	2.9	0.098	0.114	
D1	1.2	1.8	0.047	0.071	
Т	4.8	5.3	0.189	0.209	
T1	0.8	1.5	0.031	0.059	
d	_	0.2	_	0.008	
H1	1.8	2.2	0.071	0.087	
Н	1.9	2.5	0.075	0.098	
L	3.9	4.6	0.154	0.181	

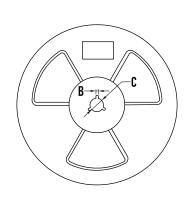
Packaging Tape - SMA

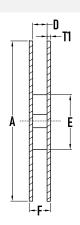




SYMBOL	MILLIMETER
A0	2.70
В0	5.10±0.1
d0	1.50±0.1
d1	1.50±0.1
Е	1.75±0.1
F	5.50±0.1
K0	2.40±0.1
Р	4.00±0.1
P0	4.00±0.1
P1	2.00±0.1
W	12.00±0.1
Т	0.2±0.02

Packaging Reel





SYMBOL	MILLIMETER
Α	323±2
В	3.0±0.2
С	15.0±0.5
D	13±2
E	73±2
T1	2.2±0.2
Quantity	5000PCS

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